



Product Change Notification: CENO-05NSRI920

Date:

20-Aug-2026

Product Category:

Clock And Timing - Clock Generation, Jitter Attenuators, Network Synchronization

Notification Subject:

CCB 8417 and 8451 Initial Notice: Qualification of a new die size (1.560 x 0.863 mm) for Die #2 of selected ZL3073xx, ZL3027xx, ZL3064xx, ZL3063xx, ZL8003xx, ZL8073xx, ZL8013xx, ZL8083xx, ZL3083xx, ZL3093xx, ZL8064xx and ZL8093xx device families and qualification of a new die size (1.560 x 0.863 mm) for Die #3 of selected ZL302xx, ZL306xx, ZL307xx, ZL800xx and ZL308xx device families using HR-5104 as a new die attach material available in various packages.

Affected CPNs:

[CENO-05NSRI920_Affected_CPN_08202026.pdf](#)

[CENO-05NSRI920_Affected_CPN_08202026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of a new die size (1.560 x 0.863 mm) for Die #2 of selected ZL3073xx, ZL3027xx, ZL3064xx, ZL3063xx, ZL8003xx, ZL8073xx, ZL8013xx, ZL8083xx, ZL3083xx, ZL3093xx, ZL8064xx and ZL8093xx device families and qualification of a new die size (1.560 x 0.863 mm) for Die #3 of selected ZL302xx, ZL306xx, ZL307xx, ZL800xx and ZL308xx device families using HR-5104 as a new die attach material available in various packages.

Pre and Post Summary Changes:

For ZL30735, ZL30271, ZL30273, ZL30274, ZL30642, ZL30643, ZL30645, ZL30634, ZL30732, ZL30644, ZL30734, ZL30733, ZL30632, ZL30633, ZL30635, ZL80032, ZL30631, ZL30640, ZL30641, ZL30731, ZL30634A, ZL30642A, ZL80732, ZL30640A, ZL80132, ZL30735A, ZL30732A, ZL30733A, ZL30644A, ZL30634F6022, ZL30634AF7005, ZL30642F6022, ZL30642AF7005, ZL30270, ZL30272, ZL80833AS, ZL30633AS, ZL30642AS, ZL30733AS, ZL30833A, ZL30934A, ZL30735B, ZL80132B,

ZL30633B, ZL80640B, ZL30732B, ZL80932B, ZL30632B, ZL30642B, ZL30734B, ZL30733B, ZL80034, ZL80035, ZL80833BS, ZL30631BS and ZL30631BWS device families

		Pre Change		Post Change		Change (Yes/No)
Fabrication Site	Die #1	No Change				No
	Die #2	Grace Semiconductor Manufacturing Company (Fab 1) (GC01)	Winbond Electronics Corporation (WINB)	Grace Semiconductor Manufacturing Company (Fab 1) (GC01)	Winbond Electronics Corporation (WINB)	No
Die Size	Die #1	No Change				No
	Die #2	No Change	1.460 x 1.272 mm	No Change	1.560 x 0.863 mm	Yes

For ZL30256, ZL30683, ZL30772, ZL80062, ZL30671, ZL30672, ZL30673, ZL30681, ZL30682, ZL30771, ZL30773, ZL30803, ZL30806, ZL30822, ZL30792, ZL30664, ZL30794, ZL30795, ZL30663, ZL30793, ZL30693, ZL30661, ZL30662, ZL30691, ZL30692 and ZL30791 device families

		Pre Change	Post Change	Change (Yes/No)
Fabrication Site	Die #1	No Change		No
	Die #2	No Change		No
	Die #3	Winbond Electronics Corporation (WINB)	Winbond Electronics Corporation (WINB)	No
Die Size	Die #1	No Change		No
	Die #2	No Change		No
	Die #3	1.460 x 1.272 mm	1.560 x 0.863 mm	Yes
Assembly Site		ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	No
Wire Material		Au	Au	No

Die Attach Material (Die #3)	QMI-536 (PFAS)	HR-5104 (PFAS-free)	Yes
Molding Compound Material	KE-G2250-TC	KE-G2250-TC	No
Substrate Core Material	CCL-HL832NS-LC	CCL-HL832NS-LC	No
SM Material	AUS308	AUS308	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying a new die size and new die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: January 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	August 2026					>	January 2027				
Work Week	32	33	34	35	36		01	02	03	04	05
Initial PCN Issue Date			X								
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

August 20, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_CENO-05NSRI920 Qual Plan_CCB 8451.pdf
PCN_CENO-05NSRI920 Qual Plan_CCB 8452.pdf
PCN_CENO-05NSRI920-Pre and Post Change Summary.pdf
PCN_CENO-05NSRI920-Qual Plan_CCB 8454.pdf
PCN_CENO-05NSRI920-Qual Plan_CCB 8453.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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